

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SUNGJIN KIM	01/24/2022
SHINJAE KANG	01/24/2022
JUNGSU LEE	01/24/2022
JIIN JEON	01/25/2022
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	LG ELECTRONICS INC.
<b>Street Address:</b>	128, YEOUNI-DAERO, YEONGDEUNGPO-GU
<b>City:</b>	SEOUL
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	07336
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16289502
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(213)623-2211
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<b>ATTORNEY DOCKET NUMBER:</b>	2060-5813
<b>NAME OF SUBMITTER:</b>	JEFFREY J. LOTSPEICH
<b>SIGNATURE:</b>	/Jeffrey Lotspeich/
<b>DATE SIGNED:</b>	02/22/2022
<b>Total Attachments: 2</b>	
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ASSIGNMENT

For valuable consideration, the receipt of which we acknowledge, and intending to be bound legally, we, Sungjin KIM, Shinjae KANG, Jungsu LEE, and Jiin JEON each individually assign to LG ELECTRONICS INC., a corporation formed under the laws of KOREA and having a principal place of business at 128, Yeoui-daero, Yeongdeungpo-gu, Seoul 07336 Republic of Korea, and its successors, transferees, and assignees (collectively the "Assignee"), all of our individual and joint right, title, and interest throughout the world in the subject matter (the "Subject Matter") of a patent application that names us as inventors, is titled "ELECTRONIC DEVICE", and was filed in the United States Patent and Trademark Office on February 28, 2019 as application 16/289,502 (the "Application"). We authorize the insertion of the filing date and application number above.

This Assignment assigns (a) the Application and all other applications that may be made for, and all patents, utility models, design registrations, and other rights of exclusion and inventors' certificates for, any of the Subject Matter (collectively the "Applications and Granted Rights") in every country or region, (b) the right to claim priority based on and the benefit of the filing date of any of the Applications and Granted Rights under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other applicable treaties or conventions, and (c) the right to pursue, collect, and retain in the Assignee's name or otherwise, damages and any other remedies arising from any past, present, or future infringement of the Subject Matter, the Applications and Granted Rights, and any other rights assigned by this Assignment.

We authorize the Assignee to apply for and pursue protection for any or all of the Subject Matter, the Applications and Granted Rights, and any other rights assigned by this Assignment in all countries, regions, and territories of the world, in our names or in the Assignee's name.

We represent and warrant that we have the right and power to make this Assignment and that we have not made and will not make any other assignment that conflicts with this Assignment.

We will communicate to the Assignee (or at the request of the Assignee to other parties) all known facts in any form relating to the Subject Matter, will execute and provide all oaths and declarations, statements, testimony, assignments, powers of attorney, applications, and documents, and will perform all other lawful acts necessary or desirable to secure fully to the Assignee the rights, titles, and interests assigned by this Assignment.

김성진  
Sungjin KIM

Date: 1. 24. 2022

강신재  
Shinjae KANG

Date: Jan. 24. 2022

이정수  
Jungsu LEE

Date: 1 / 24 / 2022

전지인  
Jiin JEON

Date: 1-25-2022